

## QF2036

No Clean Liquid Flux



### Product Description

QF2036 is a low solid content flux, chemically and electrically stable under various operating environments. QF2036 is specially designed to deliver the best of solderability and minimize micro-solderballs for conventional and circuit board assemblies. This no-clean and clear residue flux shows superior wetting on difficult-to-solder substrates. It is compatible with lead free applications.

### Application

QF2036 is specially formulated for spraying, foaming as well as dipping (Cu substrate) processes. Recommended onboard preheat temperature is 80 – 100 °C.

### Residue Removal

Since the residues are minimal and non-corrosive, removal is usually not required. If cleaning is required, the flux residue could be removed by any solvent or aqueous flux cleaner available in the market.

### Recommended Solvent

Asahi's complementary Solvent #2000. Solvent can be stored for about 2 years under normal storage conditions of 25°C.

### Health and Safety

Observe standard precautions for handling and use, such as well-ventilated areas and avoidance of prolonged or repeated contact with the skin. For more information, please refer to the Material Safety Data Sheet.

### Storage

Under proper storage condition, QF2036 can be stored for up to 6 months. QF2036 is flammable. Keep away from all sources of heat, sparks, flame and sunlight.

### Packaging

Available in 18kg/carboy.

### Specification

Item	Result
State	Liquid
Colour	Very pale yellow
Specific Gravity @ 25°C	0.792 +/- 0.005
JIS Z 3197 8.2.2	
Non-volatile Solid Content	
JIS Z 3197 8.1.3	3.6 +/- 0.2 wt%
Halide Content	< 0.01 wt%
JIS Z 3197 8.1.4.2.1	
Acid Value Test	20.0 +/- 2 mg KOH/g flux
IPC-TM-650 2.3.13	
JIS Z 3197 8.1.4.1	
Water Extract Resistivity	> 5 x 10 <sup>4</sup> Ω-cm
JIS Z 3197 8.1.1	
Surface Insulation Resistance (85°C, 85%RH, 168hrs)	
IPC-TM-650 2.6.3.3	> 1 x 10 <sup>8</sup> Ω, Pass
JIS Z 3197 8.5.3	> 1 x 10 <sup>11</sup> Ω, Pass
Electromigration (85°C, 88.5%RH, 596hrs)	Pass
IPC-TM-650 2.6.14.1	
Copper Corrosion Test	Pass
IPC-TM-650 2.6.15	
JIS Z 3197 8.4.1	
Copper Mirror Test	Classified as "M", Pass
IPC-TM-650 2.3.32	
JIS Z 3197 8.4.2	
Flux Activity Classification	ROM0
IPC J-STD-004	
Spread Factor	> 75% (SCS7)
JIS Z 3197 8.3.1.1	
Residue Dryness Test	Dry
IPC-TM-650 2.4.47	
JIS Z 3197 8.5.1	
Surface Finish	Shiny

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